

## Preliminary datasheet

### EasyDUAL module with CoolSiC™ Trench MOSFET and PressFIT / NTC

#### Features

- Electrical features
  - $V_{DSS} = 1200\text{ V}$
  - $I_{DN} = 15\text{ A} / I_{DRM} = 30\text{ A}$
  - Low inductive design
  - Low switching losses
- Mechanical features
  - Rugged mounting due to integrated mounting clamps
  - PressFIT contact technology
  - Integrated NTC temperature sensor
  - AlN substrate with low thermal resistance



Typical appearance

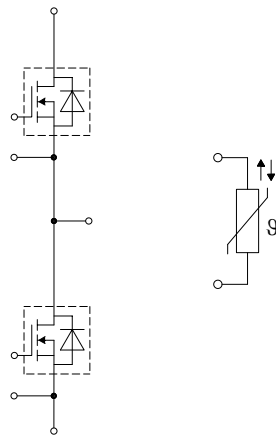
#### Potential applications

- High-frequency switching application
- DC/DC converter
- Motor drives
- UPS systems

#### Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

#### Description



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## 1 Package

**Table 1** Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	$V_{ISOL}$	RMS, $f = 50$ Hz, $t = 1$ min	3.0	kV
Internal isolation		basic insulation (class 1, IEC 61140)	AlN	
Comparative tracking index	$CTI$		> 200	
Relative thermal index (electrical)	$RTI$	housing	140	°C

**Table 2** Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module	$L_{sCE}$			14		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	$T_H = 25$ °C, per switch		5.3		mΩ
Storage temperature	$T_{stg}$		-40		125	°C
Mounting force per clamp	$F$		20		50	N
Weight	$G$			24		g

Note: The current under continuous operation is limited to 25 A rms per connector pin.

## 2 MOSFET

**Table 3** Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Drain-source voltage	$V_{DSS}$	$T_{vj} = 25$ °C	1200	V
Continuous DC drain current	$I_{DDC}$	$T_{vj} = 175$ °C, $V_{GS} = 18$ V $T_H = 125$ °C	15	A
Repetitive peak drain current	$I_{DRM}$	verified by design, $t_p$ limited by $T_{vjmax}$	30	A
Gate-source voltage, max. transient voltage	$V_{GS}$	$D < 0.01$	-10/23	V
Gate-source voltage, max. static voltage	$V_{GS}$		-7/20	V

**Table 4** Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
On-state gate voltage	$V_{GS(on)}$		15...18	V
Off-state gate voltage	$V_{GS(off)}$		-5...0	V

**Table 5** Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Drain-source on-resistance	$R_{DS(on)}$	$I_D = 15\text{ A}$	$V_{GS} = 18\text{ V}$ , $T_{vj} = 25\text{ °C}$		52.9		mΩ
			$V_{GS} = 18\text{ V}$ , $T_{vj} = 125\text{ °C}$		85.5		
			$V_{GS} = 18\text{ V}$ , $T_{vj} = 150\text{ °C}$		98.5		
			$V_{GS} = 15\text{ V}$ , $T_{vj} = 25\text{ °C}$		63.5		
Gate threshold voltage	$V_{GS(th)}$	$I_D = 6\text{ mA}$ , $V_{DS} = V_{GS}$ , $T_{vj} = 25\text{ °C}$ , (tested after 1ms pulse at $V_{GS} = +20\text{ V}$ )	3.45	4.3	5.15	V	
Total gate charge	$Q_G$	$V_{DD} = 800\text{ V}$ , $V_{GS} = -3/18\text{ V}$		0.045		μC	
Internal gate resistor	$R_{Gint}$	$T_{vj} = 25\text{ °C}$		7.5		Ω	
Input capacitance	$C_{ISS}$	$f = 100\text{ kHz}$ , $V_{DS} = 800\text{ V}$ , $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$	1.35		nF	
Output capacitance	$C_{OSS}$	$f = 100\text{ kHz}$ , $V_{DS} = 800\text{ V}$ , $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$	0.064		nF	
Reverse transfer capacitance	$C_{rSS}$	$f = 100\text{ kHz}$ , $V_{DS} = 800\text{ V}$ , $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$	0.004		nF	
$C_{OSS}$ stored energy	$E_{OSS}$	$V_{DS} = 800\text{ V}$ , $V_{GS} = -3/18\text{ V}$ , $T_{vj} = 25\text{ °C}$		26.2		μJ	
Drain-source leakage current	$I_{DSS}$	$V_{DS} = 1200\text{ V}$ , $V_{GS} = -3\text{ V}$	$T_{vj} = 25\text{ °C}$	0.01	110	μA	
Gate-source leakage current	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $T_{vj} = 25\text{ °C}$	$V_{GS} = 20\text{ V}$		400	nA	
Turn-on delay time (inductive load)	$t_{d\ on}$	$I_D = 15\text{ A}$ , $R_{Gon} = 3.9\text{ Ω}$ , $V_{DD} = 600\text{ V}$ , $V_{GS} = -3/18\text{ V}$	$T_{vj} = 25\text{ °C}$	23.1		ns	
			$T_{vj} = 125\text{ °C}$	23.1			
			$T_{vj} = 150\text{ °C}$	23.1			
Rise time (inductive load)	$t_r$	$I_D = 15\text{ A}$ , $R_{Gon} = 3.9\text{ Ω}$ , $V_{DD} = 600\text{ V}$ , $V_{GS} = -3/18\text{ V}$	$T_{vj} = 25\text{ °C}$	19.7		ns	
			$T_{vj} = 125\text{ °C}$	20.5			
			$T_{vj} = 150\text{ °C}$	20.8			
Turn-off delay time (inductive load)	$t_{d\ off}$	$I_D = 15\text{ A}$ , $R_{Goff} = 3.3\text{ Ω}$ , $V_{DD} = 600\text{ V}$ , $V_{GS} = -3/18\text{ V}$	$T_{vj} = 25\text{ °C}$	43.7		ns	
			$T_{vj} = 125\text{ °C}$	48.4			
			$T_{vj} = 150\text{ °C}$	49.8			
Fall time (inductive load)	$t_f$	$I_D = 15\text{ A}$ , $R_{Goff} = 3.3\text{ Ω}$ , $V_{DD} = 600\text{ V}$ , $V_{GS} = -3/18\text{ V}$	$T_{vj} = 25\text{ °C}$	17.3		ns	
			$T_{vj} = 125\text{ °C}$	17.3			
			$T_{vj} = 150\text{ °C}$	17.3			

(table continues...)

**Table 5 (continued) Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-on energy loss per pulse	$E_{on}$	$I_D = 15\text{ A}$ , $V_{DD} = 600\text{ V}$ , $L_\sigma = 6\text{ nH}$ , $V_{GS} = -3/18\text{ V}$ , $R_{Gon} = 3.9\ \Omega$ , $di/dt = 1.8\text{ kA}/\mu\text{s}$ ( $T_{vj} = 150\text{ }^\circ\text{C}$ )	$T_{vj} = 25\text{ }^\circ\text{C}$	0.235		mJ
			$T_{vj} = 125\text{ }^\circ\text{C}$	0.297		
			$T_{vj} = 150\text{ }^\circ\text{C}$	0.316		
Turn-off energy loss per pulse	$E_{off}$	$I_D = 15\text{ A}$ , $V_{DD} = 600\text{ V}$ , $L_\sigma = 6\text{ nH}$ , $V_{GS} = -3/18\text{ V}$ , $R_{Goff} = 3.3\ \Omega$ , $dv/dt = 27.7\text{ kV}/\mu\text{s}$ ( $T_{vj} = 150\text{ }^\circ\text{C}$ )	$T_{vj} = 25\text{ }^\circ\text{C}$	0.037		mJ
			$T_{vj} = 125\text{ }^\circ\text{C}$	0.041		
			$T_{vj} = 150\text{ }^\circ\text{C}$	0.042		
Thermal resistance, junction to heat sink	$R_{thJH}$	per MOSFET, $\lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		1.25		K/W
Temperature under switching conditions	$T_{vj\text{op}}$		-40		150	$^\circ\text{C}$

*Note: The selection of positive and negative gate-source voltages impacts losses and the long-term behavior of the MOSFET and body diode. The design guidelines described in Application Notes AN 2018-09 and AN 2021-13 must be considered to ensure sound operation of the device over the planned lifetime.*

### 3 Body diode (MOSFET)

**Table 6 Maximum rated values**

Parameter	Symbol	Note or test condition	Values	Unit
DC body diode forward current	$I_{SD}$	$T_{vj} = 175\text{ }^\circ\text{C}$ , $V_{GS} = -3\text{ V}$ $T_H = 125\text{ }^\circ\text{C}$	5	A

**Table 7 Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Forward voltage	$V_{SD}$	$I_{SD} = 15\text{ A}$ , $V_{GS} = -3\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		4.2	5.35	V
			$T_{vj} = 125\text{ }^\circ\text{C}$		3.9		
			$T_{vj} = 150\text{ }^\circ\text{C}$		3.85		

### 4 NTC-Thermistor

**Table 8 Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	$R_{25}$	$T_{NTC} = 25\text{ }^\circ\text{C}$		5		k $\Omega$
Deviation of $R_{100}$	$\Delta R/R$	$T_{NTC} = 100\text{ }^\circ\text{C}$ , $R_{100} = 493\ \Omega$	-5		5	%

**(table continues...)**

**Table 8** (continued) **Characteristic values**

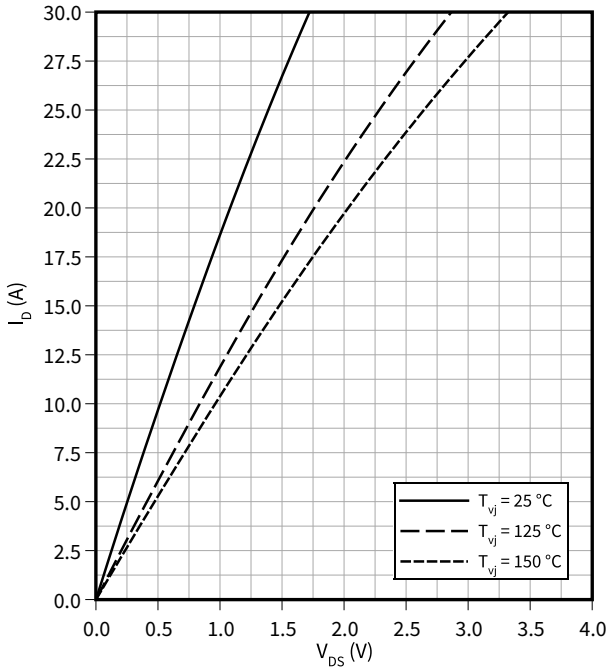
Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Power dissipation	$P_{25}$	$T_{NTC} = 25\text{ °C}$			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		3433		K

Note: Specification according to the valid application note.

## 5 Characteristics diagrams

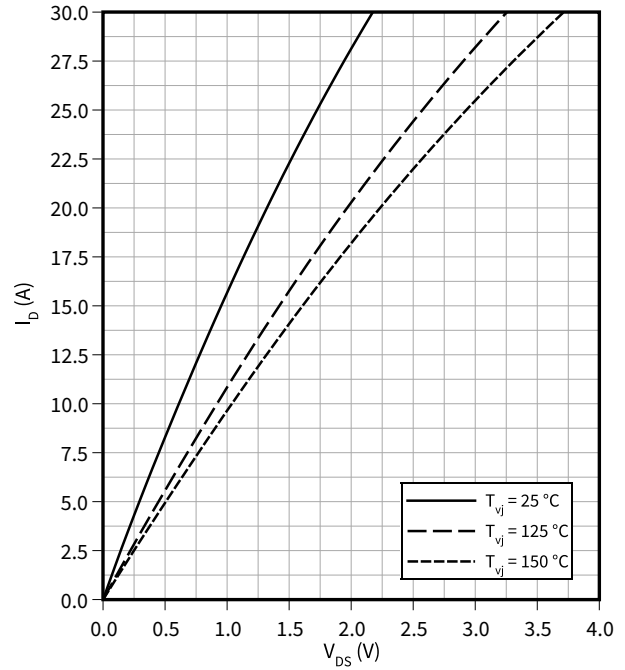
**Output characteristic (typical), MOSFET**

$I_D = f(V_{DS})$   
 $V_{GS} = 18\text{ V}$



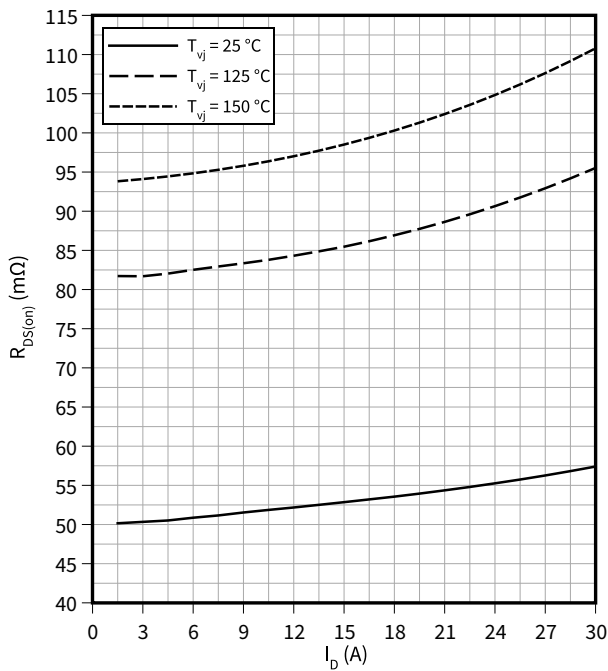
**Output characteristic (typical), MOSFET**

$I_D = f(V_{DS})$   
 $V_{GS} = 15\text{ V}$



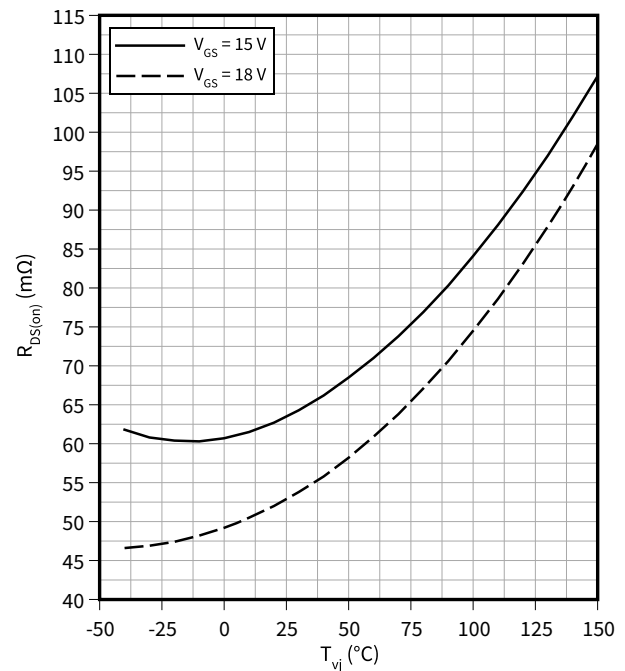
**Drain source on-resistance (typical), MOSFET**

$R_{DS(on)} = f(I_D)$   
 $V_{GS} = 18\text{ V}$



**Drain source on-resistance (typical), MOSFET**

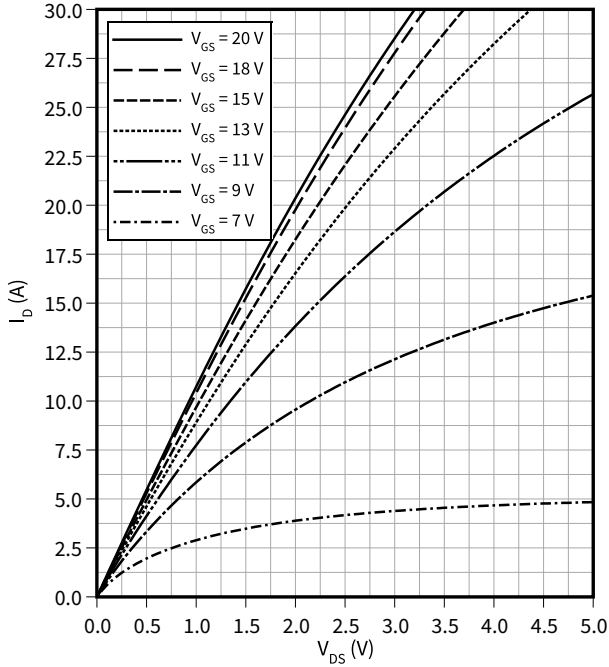
$R_{DS(on)} = f(T_{vj})$   
 $I_D = 15\text{ A}$



5 Characteristics diagrams

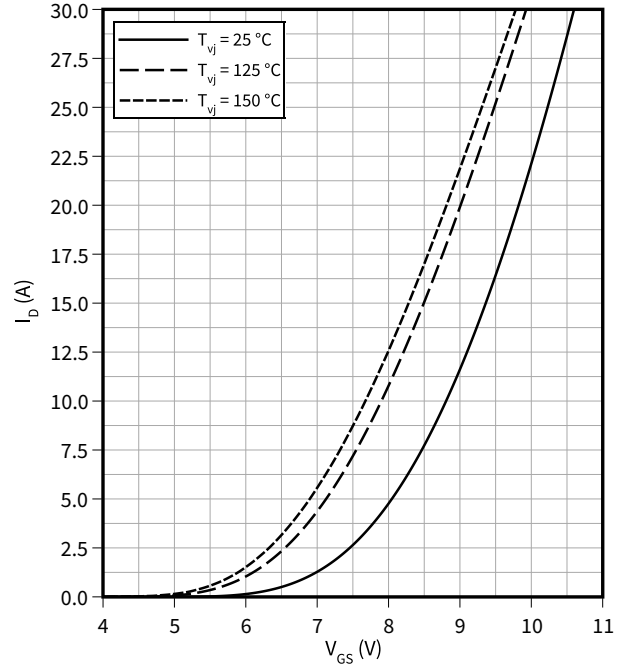
**Output characteristic field (typical), MOSFET**

$I_D = f(V_{DS})$   
 $T_{vj} = 150\text{ °C}$



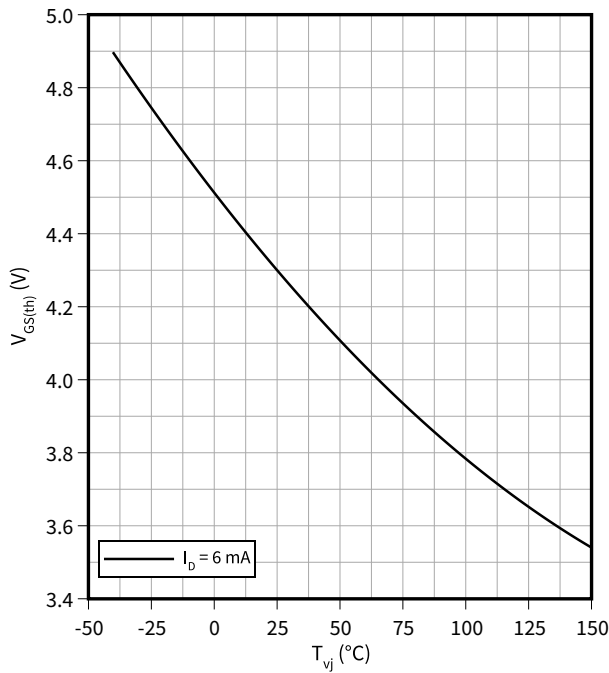
**Transfer characteristic (typical), MOSFET**

$I_D = f(V_{GS})$   
 $V_{DS} = 20\text{ V}$



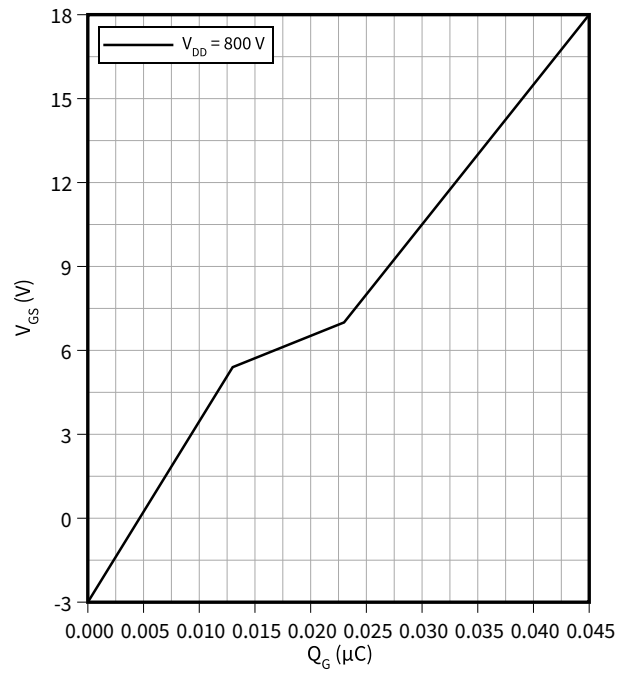
**Gate-source threshold voltage (typical), MOSFET**

$V_{GS(th)} = f(T_{vj})$   
 $V_{GS} = V_{DS}$



**Gate charge characteristic (typical), MOSFET**

$V_{GS} = f(Q_G)$   
 $I_D = 15\text{ A}, T_{vj} = 25\text{ °C}$

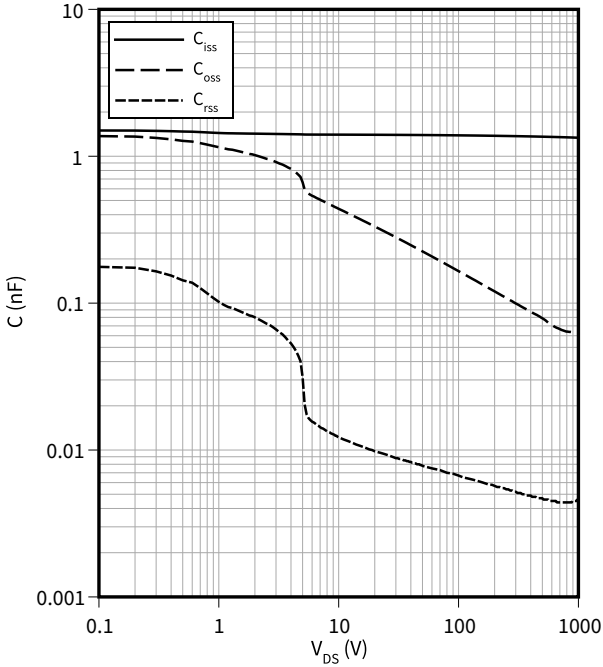




5 Characteristics diagrams

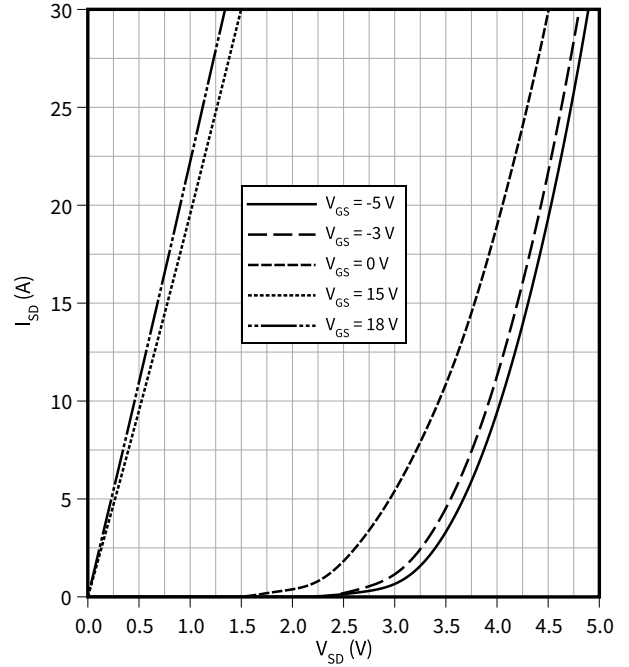
**Capacity characteristic (typical), MOSFET**

$C = f(V_{DS})$   
 $f = 100 \text{ kHz}, T_{vj} = 25 \text{ }^\circ\text{C}, V_{GS} = 0 \text{ V}$



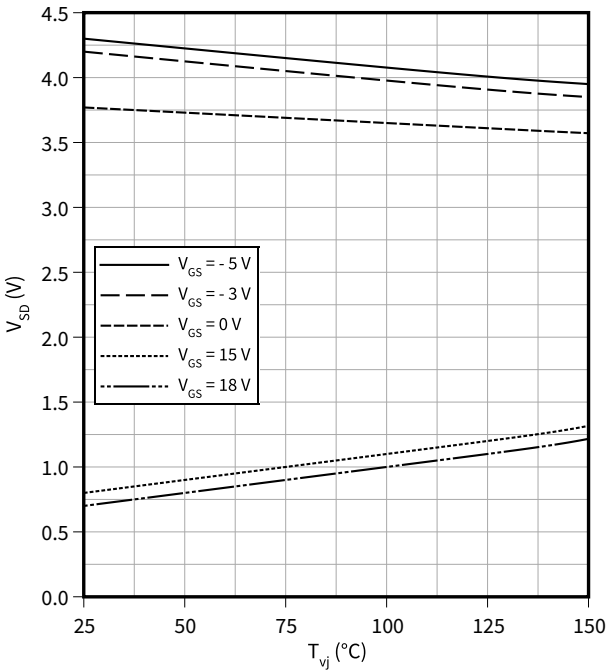
**Forward characteristic body diode (typical), MOSFET**

$I_{SD} = f(V_{SD})$   
 $T_{vj} = 25 \text{ }^\circ\text{C}$



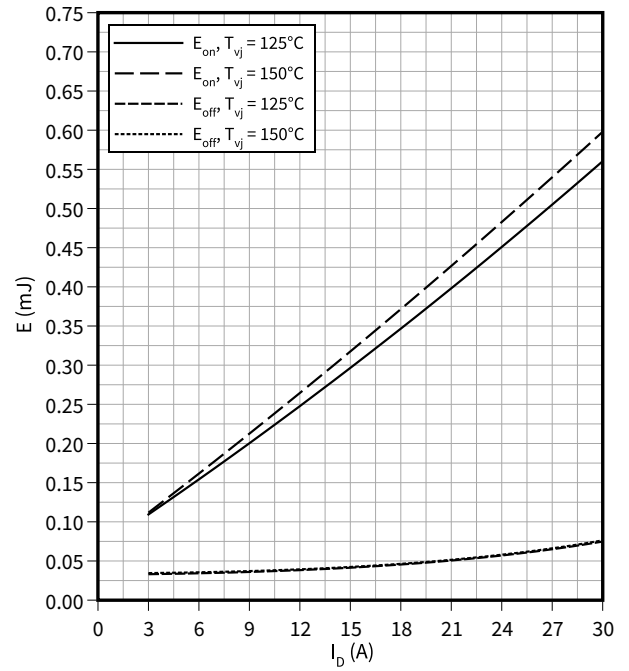
**Forward voltage of body diode (typical), MOSFET**

$V_{SD} = f(T_{vj})$   
 $I_{SD} = 15 \text{ A}$



**Switching losses (typical), MOSFET**

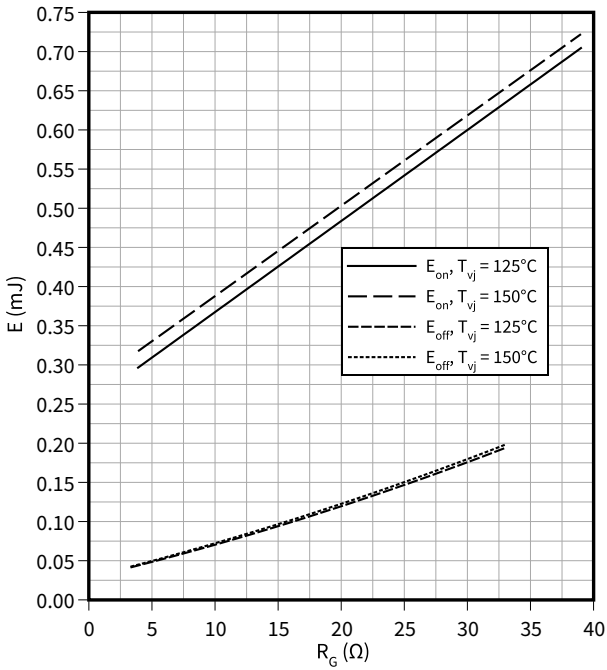
$E = f(I_D)$   
 $R_{Goff} = 3.3 \text{ } \Omega, R_{Gon} = 3.9 \text{ } \Omega, V_{DD} = 600 \text{ V}, V_{GS} = -3/18 \text{ V}$



**Switching losses (typical), MOSFET**

$E = f(R_G)$

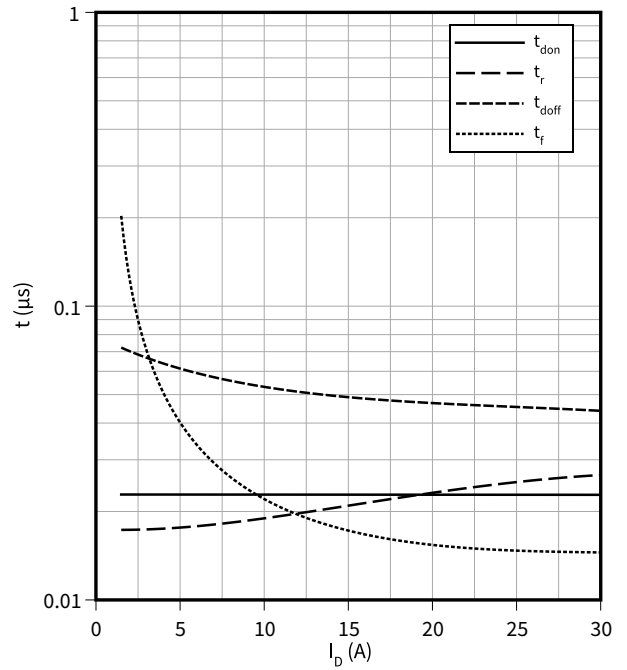
$V_{DD} = 600\text{ V}, I_D = 15\text{ A}, V_{GS} = -3/18\text{ V}$



**Switching times (typical), MOSFET**

$t = f(I_D)$

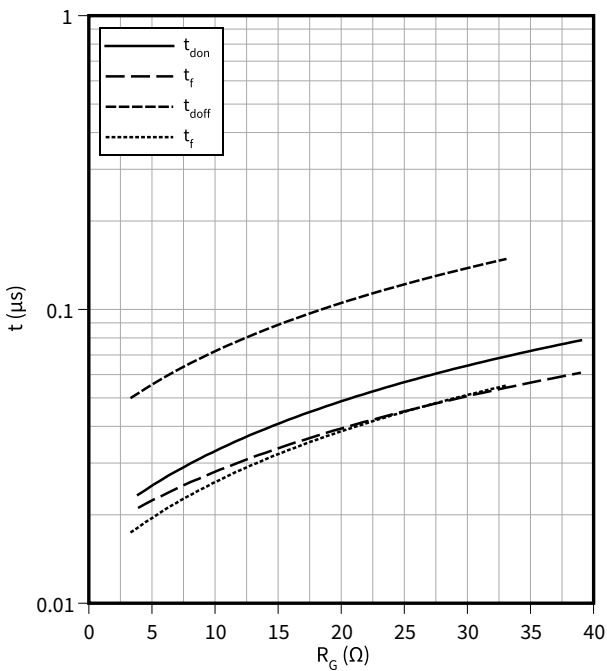
$R_{Goff} = 3.3\ \Omega, R_{Gon} = 3.9\ \Omega, V_{DD} = 600\text{ V}, T_{vj} = 150\text{ }^\circ\text{C}, V_{GS} = -3/18\text{ V}$



**Switching times (typical), MOSFET**

$t = f(R_G)$

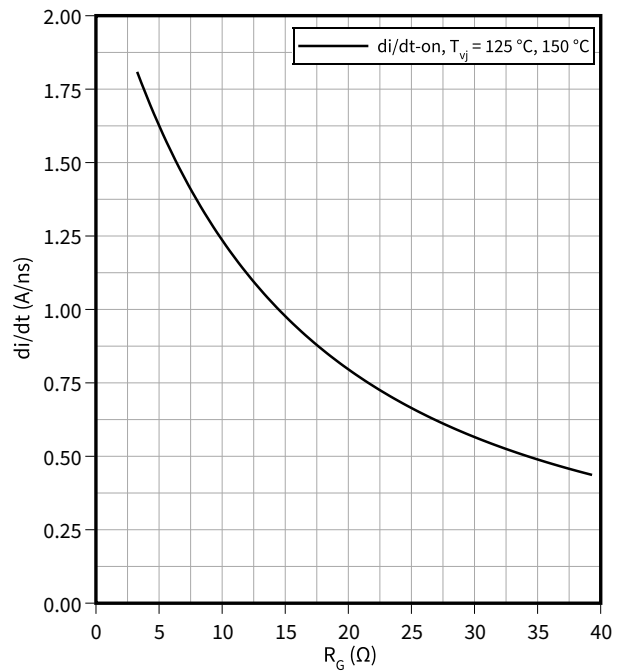
$V_{DD} = 600\text{ V}, I_D = 15\text{ A}, T_{vj} = 150\text{ }^\circ\text{C}, V_{GS} = -3/18\text{ V}$



**Current slope (typical), MOSFET**

$di/dt = f(R_G)$

$V_{DD} = 600\text{ V}, I_D = 15\text{ A}, V_{GS} = -3/18\text{ V}$

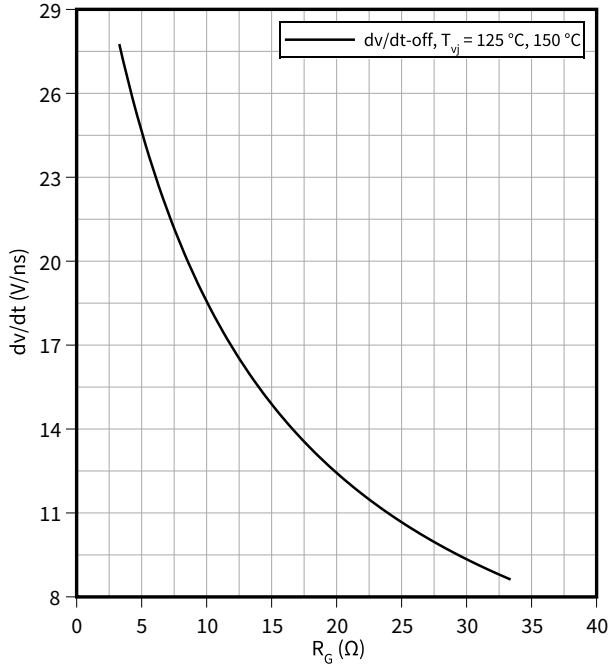


5 Characteristics diagrams

**Voltage slope (typical), MOSFET**

$dv/dt = f(R_G)$

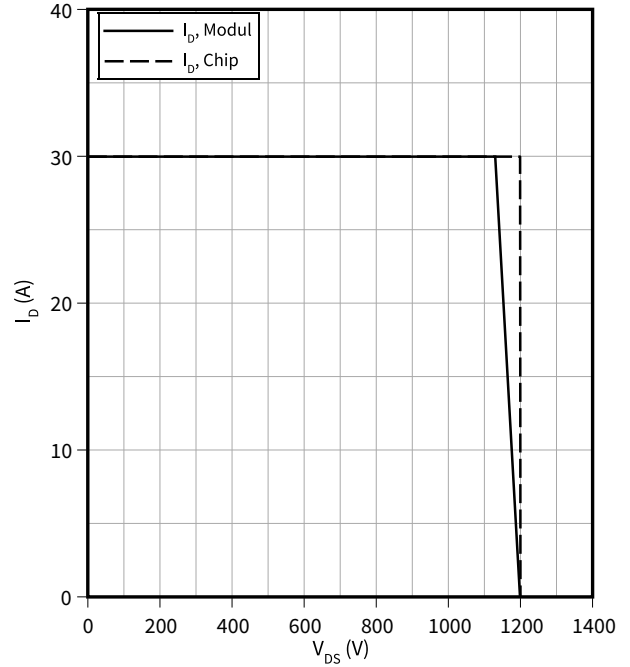
$V_{DD} = 600\text{ V}, I_D = 15\text{ A}, V_{GS} = -3/18\text{ V}$



**Reverse bias safe operating area (RBSOA), MOSFET**

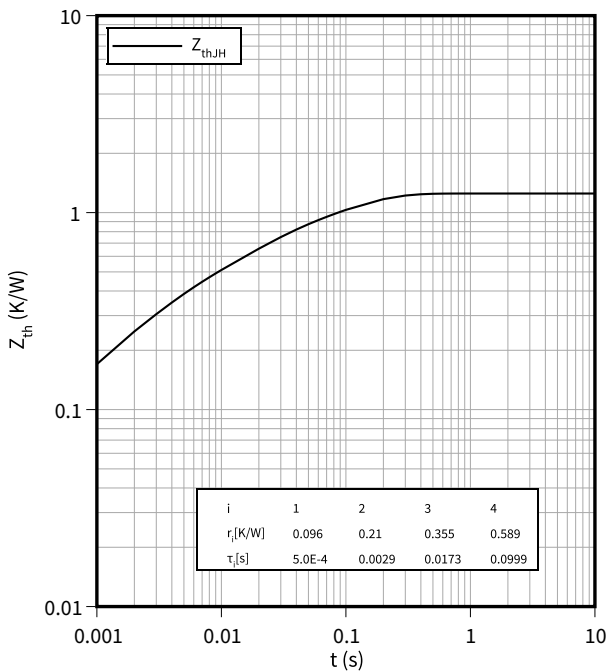
$I_D = f(V_{DS})$

$R_{Goff} = 3.3\ \Omega, T_{vj} = 150\ \text{°C}, V_{GS} = -3/18\ \text{V}$



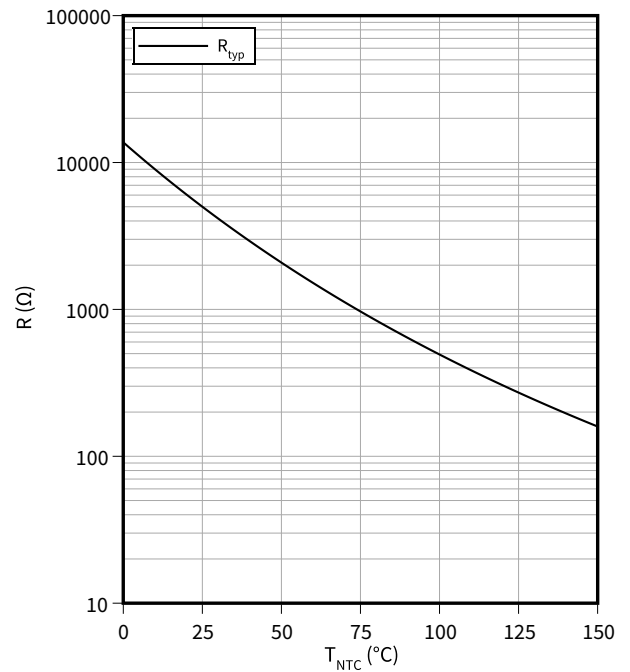
**Transient thermal impedance, MOSFET**

$Z_{th} = f(t)$



**Temperature characteristic (typical), NTC-Thermistor**

$R = f(T_{NTC})$



## 6 Circuit diagram

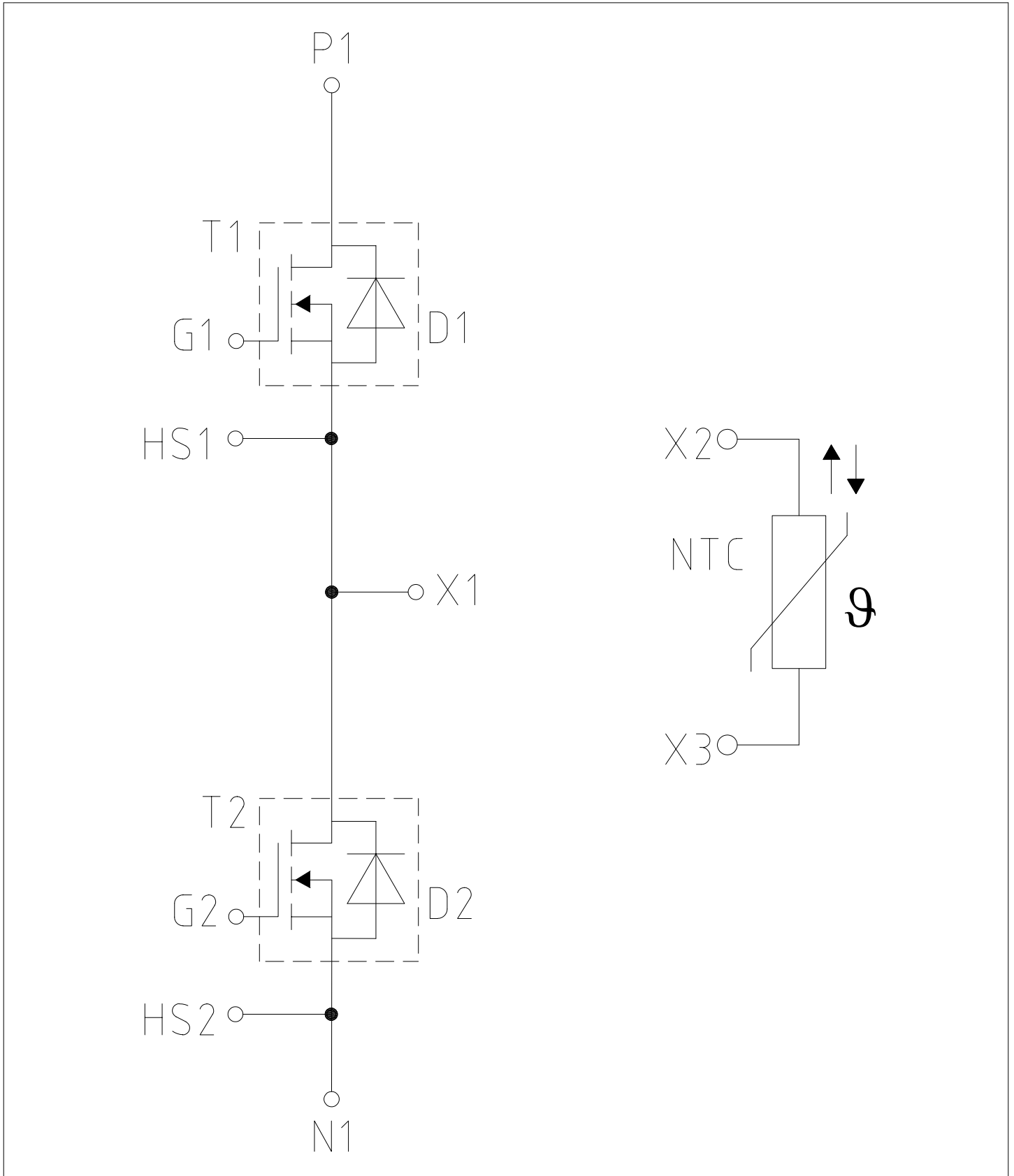


Figure 1

7 Package outlines

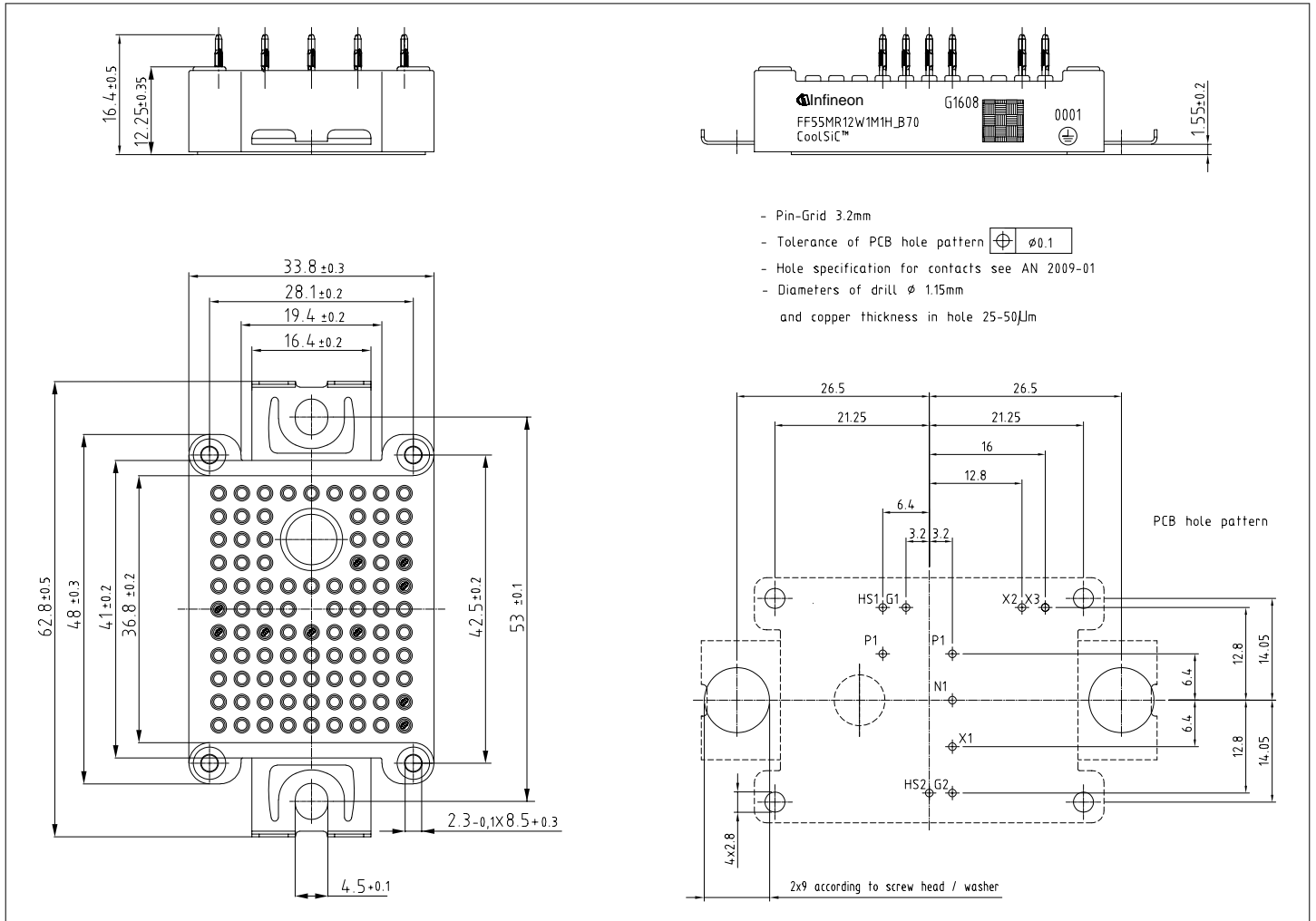


Figure 2

## 8 Module label code


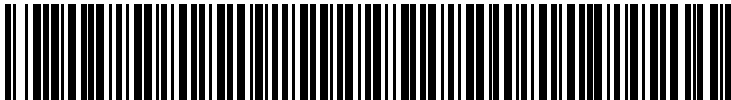
Module label code			
Code format	Data Matrix	Barcode Code128	
Encoding	ASCII text	Code Set A	
Symbol size	16x16	23 digits	
Standard	IEC24720 and IEC16022	IEC8859-1	
Code content	Content	Digit	Example
	Module serial number	1 - 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 - 21	15
	Date code (production week)	22 - 23	30
Example	 		
	71549142846550549911530		71549142846550549911530

Figure 3